JJMICROELECTRONICS

70V, 230A, 1.8mΩ N-channel Power SGT MOSFET JMSH0702PE

Features

- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED
- 100% ΔVds TESTED
- Halogen-free; RoHS-compliant
- Pb-free plating

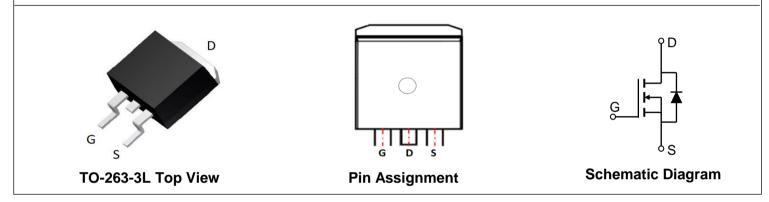
Applications

- Load Switch
- PWM Application
- Power Management

Product Summary

Parameters	Value	Unit
V _{DSS}	70	V
V _{GS(th)_Typ}	3.0	V
I _D (@V _{GS} =10V)	230	А
$R_{DS(ON)_Typ}$ (@V _{GS} =10V	1.8	mΩ





Ordering Information

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMSH0702PE	SH0702P	3	Tape&Reel	TO-263-3L	800	4000

Absolute Maximum Ratings (@ $T_c = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter		Value	Unit
V _{DS}	Drain-to-Source Voltage	Э	70	V
V _{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	$T_{\rm C} = 25^{\circ}{\rm C}$	230	٨
Ι _D	Continuous Drain Current	$T_{\rm C} = 100^{\circ}{\rm C}$	163	A
I _{DM}	Pulsed Drain Current ⁽¹⁾		Refer to Fig.4	A
E _{AS}	Single Pulsed Avalanche Energy ⁽²⁾		389	mJ
P _D	POWAr Liegingtion	$T_{\rm C} = 25^{\circ}{\rm C}$	238	W
		$T_{\rm C} = 100^{\circ}{\rm C}$	95	٧V
T _J , T _{STG}	Junction & Storage Temperature Range		-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Мах	Unit
R _{θJA}	Thermal Resistance, Junction to Ambient ⁽³⁾	71	°C/W
R _{eJC}	Thermal Resistance, Junction to Case	0.5	C/ VV



Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0V$	70	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 56V, V_{GS} = 0V$	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Cha	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, \ I_D = 250 \mu A$	2.1	3.0	3.9	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 10V, I_D = 20A$	-	1.8	2.5	mΩ
	ic Characteristics				1	•
R_g	Gate Resistance	f = 1MHz	-	2.4	-	Ω
C _{iss}	Input Capacitance		-	3007	-	pF
C _{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 35V,$ f = 1MHz	-	1068	-	pF
C _{rss}	Reverse Transfer Capacitance		-	50	-	pF
Qg	Total Gate Charge		-	49	-	nC
Q _{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 35V, I_D = 20A$	-	15	-	nC
Q_{gd}	Gate Drain("Miller") Charge	V DS = 00 V, ID = 20/V	-	14	-	nC
Switch	ing Characteristics					
t _{d(on)}	Turn-On DelayTime		-	15	-	ns
t _r	Turn-On Rise Time	V _{GS} = 10V, V _{DD} = 35V	-	32	-	ns
t _{d(off)}	Turn-Off DelayTime	I_{D} = 20A, R_{GEN} = 6.2 Ω	-	40	-	ns
t _f	Turn-Off Fall Time		-	32	-	ns
Body D	Diode Characteristics					
I _S	Maximum Continuous Body Diode Forward Current			-	230	А
I _{SM}	Maximum Pulsed Body Diode Forward Curre	num Pulsed Body Diode Forward Current		-	919	А
$V_{\rm SD}$	Body Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 20A$	-		1.2	V
trr	Body Diode Reverse Recovery Time		-	48	-	ns
Qrr	Body Diode Reverse Recovery Charge	– I _F = 20A, di/dt = 100A/us	-	55	-	nC

Electrical Characteristics ($T_J = 25^{\circ}C$ unless otherwise specified)

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

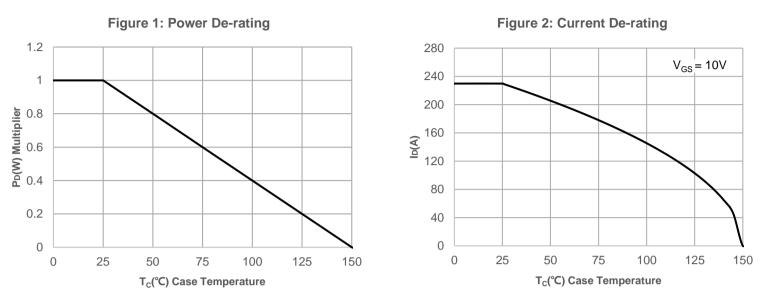
2. E_{AS} condition: Starting T_J =25C, V_{DD} =35V, V_G =10V, R_G =25ohm, L=3mH, I_{AS} =16.1A, V_{DD} =0V during time in avalanche.

3. $R_{\theta JA}$ is measured with the device mounted on a minimum recommended $\,$ pad layout..

4. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 0.5%.

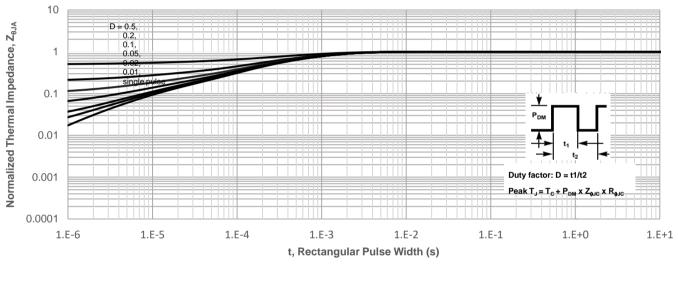


All product information is copyrighted and subject to legal disclaimers.

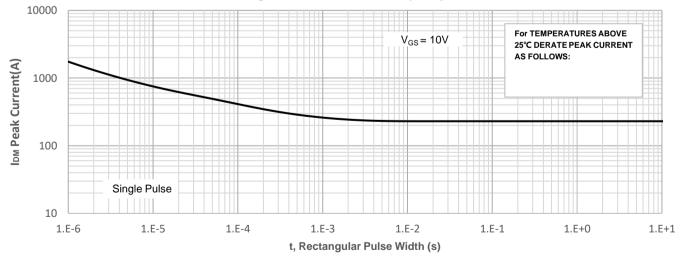


Typical Performance Characteristics

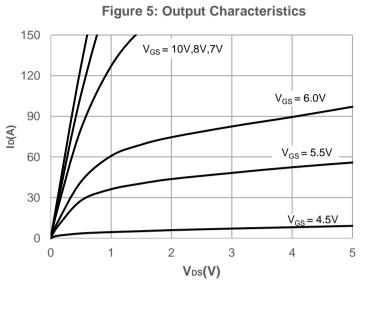












Typical Performance Characteristics

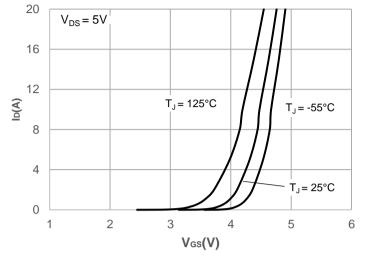


Figure 6: Typical Transfer Characteristics

Figure 7: On-resistance vs. Drain Current 12.00 10.00 8.00 $R_{DS(ON)}(m\Omega)$ 6.00 4.00 $V_{GS} = 10V$ 2.00 0.00 0 5 15 20 10

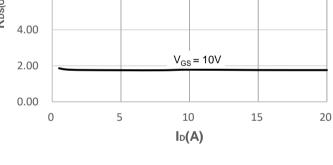


Figure 9: Gate Charge Characteristics

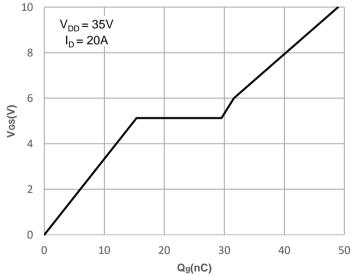


Figure 8: Body Diode Characteristics

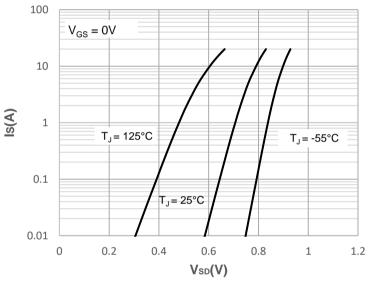
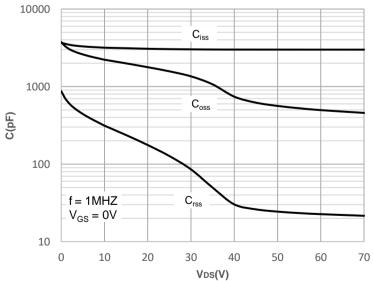
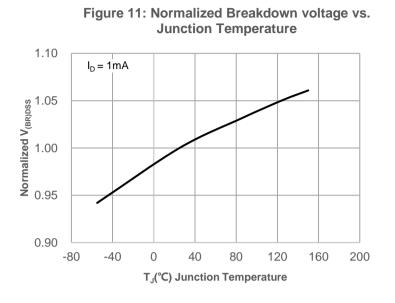


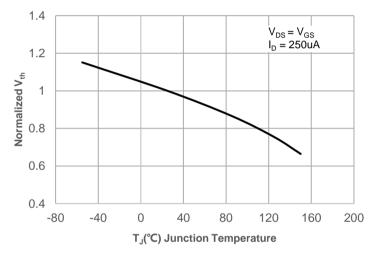
Figure 10: Capacitance Characteristics



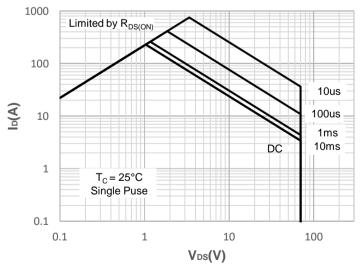
Typical Performance Characteristics

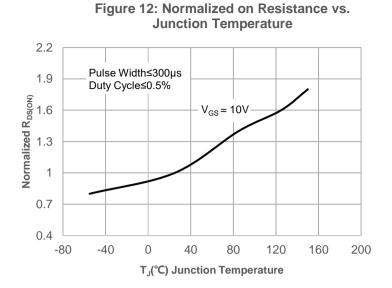


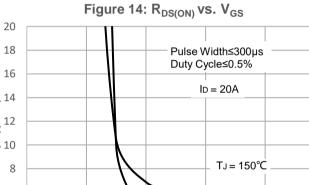


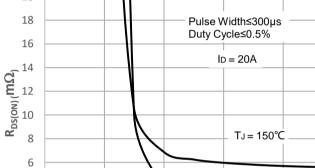






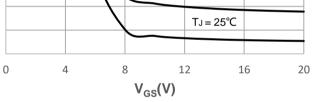






4

2





Test Circuit

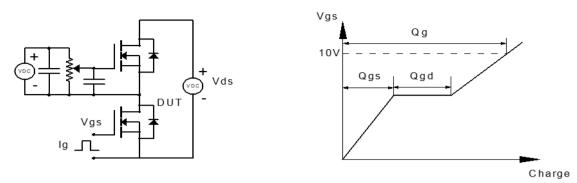


Figure 1: Gate Charge Test Circuit & Waveform

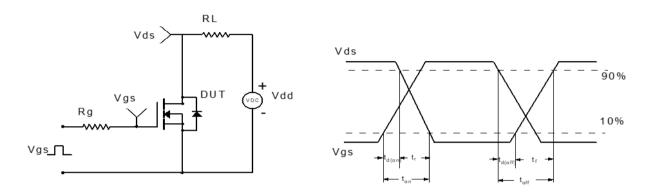


Figure 2: Resistive Switching Test Circuit & Waveform

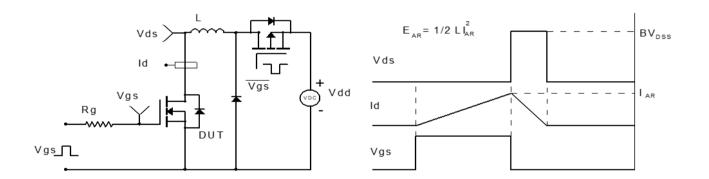


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

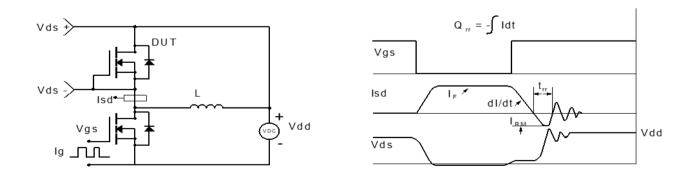
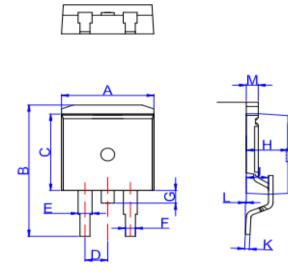


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(TO-263-3L)



TO-263

			Dime	ensions		
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
А	9.90		10.20	0.390		0.402
В	14.70		15.80	0.579		0.622
С	9.4		9.6	0.37		0.378
D		2.54			0.100	
E	1.20		1.40	0.047		0.055
F	0.75		0.85	0.029		0.033
G			1.75			0.069
н	4.40		4.70	0.173		0.185
J	2.30		2.70	0.091		0.106
к	0.38		0.55	0.015		0.022
L	0	0.10	0.25	0	0.004	0.010
м	1.25		1.35	0.049		0.053

Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics Co.,Ltd assumes no responsibility for the consequences of use without consideration for such information nor use beyond it. Information mentioned in this document is subject to change without notice, apart from that when an agreement is signed, Jiangsu JieJie complies with the agreement. Products and information provided in this document have no infringement of patents. Jiangsu JieJie assumes no responsibility for any infringement of other rights of third parties which may result from the use of such products and information.

I is a registered trademark of Jiangsu JieJie Microelectronics Co.,Ltd.

